

AMENDMENTS TO THE CLAIMS

Claim 1 (Amended) A polishing apparatus comprising:

a turntable;

an abrasive cloth mounted on an upper surface of said turntable;

a top ring disposed above said turntable for supporting a workpiece to be polished and pressing the workpiece against said abrasive cloth;

moving means for moving said turntable and said top ring relative to each other, thereby to cause said abrasive cloth supported by said turntable to polish a surface of the workpiece pressed by said top ring against said abrasive cloth, during which polishing at least one area of the surface of the workpiece tends to be polished more intensively at a higher polishing rate than at least one other area of the surface of the workpiece, thus tending to create polishing irregularities on the surface of the workpiece; and

said abrasive cloth having [an actuatable region] actuatable regions individually and independently operable to be selectively caused to form therein recesses [a recess], and said [recess] recesses being located at [a position] positions relative to said top ring to come into contact with the at least one area of the surface of the workpiece and thus forming means to perform less intensive polishing of the at least one area, while regions [a region] of said abrasive cloth other than at said [recess is] recesses are operable to contact the at least one other area of the surface of the workpiece to perform a more intensive polishing thereof, and thereby to correct the polishing irregularities.

Claim 2 (Amended) A polishing apparatus according to claim 1, wherein said positions [position] of said [recess is] recesses are selectable in a radial direction of said turntable.

Claim 22 (Amended) A polishing apparatus for polishing a semiconductor wafer to a flat mirror finish, said apparatus comprising:

an abrasive cloth having a contact surface which contacts a surface of a wafer to be polished during polishing; [and]

a top ring for supporting the wafer and pressing the wafer against said abrasive cloth; and

moving means for moving a plurality of portions of said abrasive cloth to be higher than another portion of said abrasive cloth so that [wherein a] said plurality of portions of said abrasive cloth are individually and independently pressed against the wafer by air pressures.

Claim 26 (Cancel)